

Appln. No. 09/814,486

Attorney Docket No. 10541-2108

I. Amendments to the Specification

Please replace the paragraph beginning at page 13, line 13 with the following amended paragraph:

In the eighth step of process 10, which is shown best in Figure 1(g), certain portions of dielectric material 54 are removed from pre-circuit assembly 56, effective to form recesses 58, 60, 62, 64, 66, 68 which terminate upon a unique one of the members 34, recesses 70, 72, 74, 76, 78, which terminate upon a unique one of the members 44, and recess 80, which terminates upon member 42, thereby forming pre-circuit assembly 82, ~~thereby forming a pre-circuit assembly 57~~. In one non-limiting embodiment, recesses 58-78 are formed by a known conventional photoimaging process (e.g., when the dielectric material 54 which is applied in the sixth step of process 10 which is shown in Figure 1(f), comprises a photo-imagable and/or photosensitive material, recesses 58-78 may be formed by a known conventional photoimaging process). In a further non-limiting embodiment of the invention, recesses 58-78 are formed by a known conventional laser drilling process (e.g., when the dielectric material 54 which is applied in the sixth step of process 10 which is shown best in Figure 1(f), comprises a non-photo-imagable material, recesses 58-78 may be formed by a known conventional laser driller process).